Contactless Sheet Resistance/Resistivity Measurement
Model 1800CH-2.5” OEM - Ideally large samples, 450 mm wafer maximum

Characterization of
* All compound semiconductor materials
  ➢ epi, annealed ion-implants on semi-insulating and some doped substrates
* Silicon wafers
  ➢ bulk Si, epi, annealed ion-implants, and POCl3 doping uniformity on high resistivity substrates
* Thin film metallization
  ➢ Contact factory for details

Benefits
* Lower operation cost
* Perform non-destructive measurements
* Minimal non-contact calibration
* Measurement heads are permanent
* Measurement range selected easily
* No product wafer contamination
* Ideal for mounted inline in production line

Operating Characteristics
* Precise voltage regulation for tight linearity and consistently repeatable results

Sample Handling and Sensing
* Automatic drift compensation
* Software-selectable resistivity ranges

Nondestructive Measurement of Semiconductor Wafers

Specifications

<table>
<thead>
<tr>
<th>Range *</th>
<th>Sheet Res. (ohm/sq.)</th>
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</thead>
<tbody>
<tr>
<td>Hi</td>
<td>16 - 3000</td>
</tr>
<tr>
<td>Lo</td>
<td>0.16 - 16</td>
</tr>
<tr>
<td>XLo</td>
<td>0.035 - 1.6</td>
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</tbody>
</table>

*each range sold separately

Figure 1: Model 1800CH-2.5”